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PLATINUM PALLADIUM SILVER CONDUCTOR

9566

ESL 9566 is a general purpose conductor for use in hybrid circuits. It has excellent solderability and low resistivity. It makes good electrical contact with ESL 8836 gold conductor, thermosonic gold wire bonding, and with ESL 8835-1B, thermal printhead terminations. ESL 9566 can also be used with other ESL gold inks in high reliability circuits.

PASTE DATA

RHEOLOGY:	Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5±0.5°C)	225±25 Pa•s
BONDING MECHANISM:	Mixed
SHELF LIFE:(25°C)	6 months

PROCESSING

SCREEN MESH/EM	IULSION:	325/12.5 μm
LEVELING TIME: (2	25°C)	5-10 minutes
DRYING AT 125°C:		10-15 minutes
FIRING RANGE:		850°C-930°C
	OPTIMUM:	850°C
	TIME AT PEAK:	10-12 minutes
RATE OF ASCENT/DESCENT:		60°C-100°C/minute
SUBSTRATE OF C	ALIBRATION:	96% alumina, beryllia
THINNER:		ESL 401

ESL Affiliates

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TYPICAL PROPERTIES

FIRED THICKNESS:		12.5±2.5 μm
RESISTIVITY:		\leq 8 mΩ/sq.
PRINTING RESOLUTION: (Line/Space)		500 μm x 500 μm
SOLDER WETTABILITY: (RMA flux, 5 sec. dip) (62Sn/36Pb/2Ag, 220°C±5°C)		Excellent
SOLDER LEACH: (No. of 10 sec. dip to double resistance of 0.25 mm wide x 100 mm long conductor)		
	62 Sn/36 Pb/2 Ag (220°C±5°C)	10
ADHESION: (90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag)		
	Initial pull strength:	≥ 70 N
	Aged 48 hours at 150°C:	≥ 60 N
ULTRASONIC WIRE BOND:		
	(25 µm Al wire)	6.0-6.2 g
	(Aged 48 hours at 150°C)	4.5-5.0 g
THERMOSONIC WIRE BOND:		
	(25 μm Au wire)	5.5-6.5 g

9566 9810-C

CAUTION: Proper industrial safety precautions should be exercised in using these products. Use with adequate ventilation. Avoid prolonged contact with skin or inhalation of any vapors emitted during use or heating of these compositions. The use of safety eye goggles, gloves or hand protection creams is recommended. Wash hands or skin thoroughly with soap and water after using these products. Do not eat or smoke in areas where these materials are used. Refer to appropriate MSDS sheet.

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